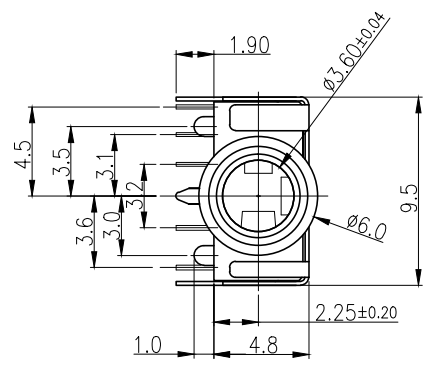
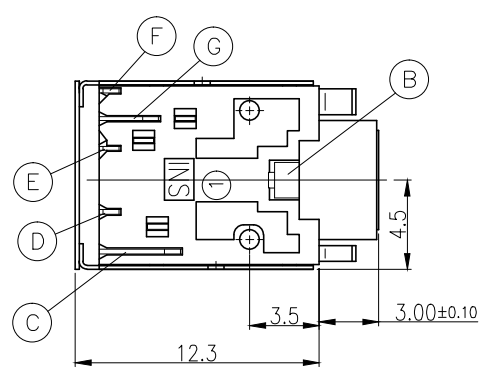
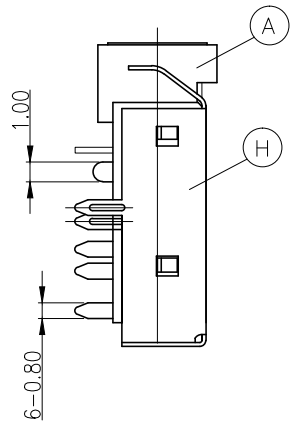
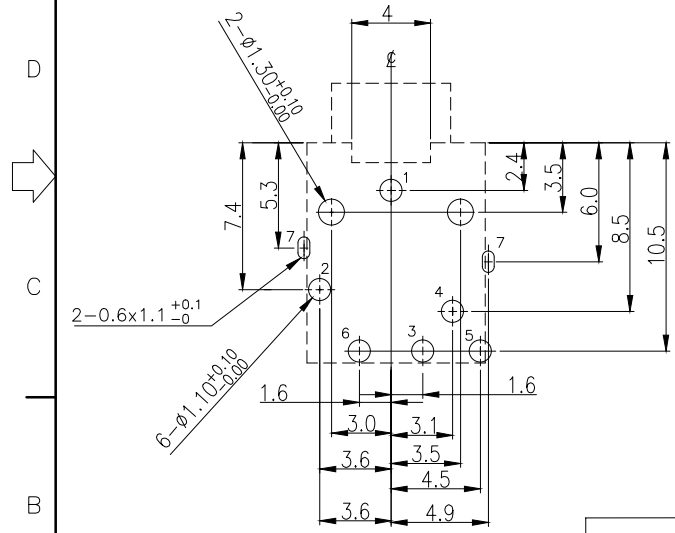


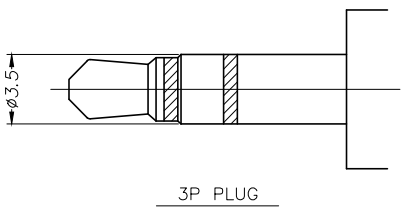
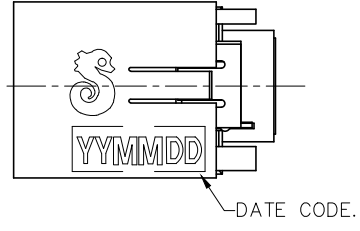
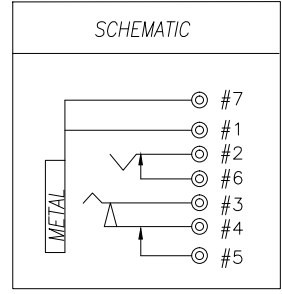
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO. T080415-1A	Bruce	2008.04.18
B	ECN NO:S140739	SEAN	2014.07.23



- SPECIFICATIONS :
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE : 30mΩ MAX. (200mΩ MAX:METAL TO EARTH TO SHIELDING)
 - INSULATION VOLTAGE WITHSTAND : 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST : 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE : 0.4 - 3Kg.
 - WITHDRAWAL FORCE : 0.3 - 2Kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE : 50MΩ MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKING : TAPE & REEL.
 - TO CONFORM TO THE SINGATRON HSF SPECIFICATION"
 - GREEN PRODUCT IDENTIFICATION MARK ON JACK
 - GREEN PRODUCT IDENTIFICATION LABEL ON PACKING: **G.P. PASS**
 - FOR LEAD-FREE PROCESS.



RECOMMENDED PCB LAYOUT
TOP VIEW(TOL.±0.05)



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	Ni 50u" min. Cu#80u" min.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA Sn120u" ON SOLDER ALL OVER Ni50u".
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	Ag 20u"MIN.,Ni 50u"MIN.
D	SHUNT TERMINAL-A	1	BRASS 0.25t	
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25	BLACK COLOR
B	EARTH	1	COPPER ALLOY 0.3t	
A	BODY+ METAL	1	HIGH TEMP.U.L 94V-0 + BRASS	GOLD FLASH Ni#1.5um
UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS: ANGLES:		TITLE: 3.5Ø PHONE JACK		
X :±0.5	X :±2°	DWN	SEAN	PART NO. 2SJ-S351-S35
X.X :±0.3	X.X :±1°	CHKD	Cerry	SCALE:4/1 UNIT: mm
X.XX :±0.2		APVD	MAX	SIZE: A3 SHEET: 10F1 REV: B
CUSTOMER COPY				